

**Table I–15 to Subpart I of Part 98–Default Emission Factors (1–U<sub>ij</sub>) for Gas Utilization Rates (U<sub>ij</sub>) and By-Product Formation Rates (B<sub>ijk</sub>) for MEMS Manufacturing for use with the Stack Test Method**

All Processes	Process Gas i											
	CF <sub>4</sub>	C <sub>2</sub> F <sub>6</sub>	CHF <sub>3</sub>	CH <sub>2</sub> F <sub>2</sub>	C <sub>3</sub> F <sub>8</sub>	c-C <sub>4</sub> F <sub>8</sub>	NF <sub>3</sub> Remote	NF <sub>3</sub>	SF <sub>6</sub>	C <sub>4</sub> F <sub>6</sub>	C <sub>5</sub> F <sub>8</sub>	C <sub>4</sub> F <sub>8</sub> O
1-U <sub>i</sub>	0.9	0.6	0.4	0.1	0.4	0.1	0.2	0.2	0.2	0.1	0.1	0.1
BCF <sub>4</sub>	NA	0.2	0.07	0.08	0.1	0.1	<sup>a</sup> 0.02	0.09	NA	0.3	0.1	0.1
BC <sub>2</sub> F <sub>6</sub>	NA	NA	NA	NA	NA	<sup>a</sup> 0.04	NA	NA	NA	0.2	0.04	NA
BC <sub>3</sub> F <sub>8</sub>	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA

**Notes:** NA = Not applicable; i.e., there are no applicable emission factor measurements for this gas. This does not necessarily imply that a particular gas is not used in or emitted from a particular process sub-type or process type.

<sup>a</sup> Estimate reflects presence of low-k, carbide and multi-gas etch processes that may contain a C-containing fluorinated GHG additive.